

Title (en)
HEAT FLOW DEVICE

Title (de)
WÄRMEFLUSSVORRICHTUNG

Title (fr)
DISPOSITIF A ECOULEMENT DE CHALEUR

Publication
EP 2047201 A1 20090415 (FR)

Application
EP 07823290 A 20070717

Priority
• FR 2007001223 W 20070717
• FR 0653016 A 20060718

Abstract (en)
[origin: WO2008009812A1] A device comprises equipment (101) with a heat source, a cold part (102) relative to the equipment, and a thermal conductor element (103) capable of conducting the heat from the equipment to the cold part. The element (103) is such that, under certain thermal conditions above a given thermal condition, the equipment and the cold part are essentially thermally isolated.

IPC 8 full level
F28F 13/00 (2006.01)

CPC (source: EP US)
F28F 13/00 (2013.01 - EP US); **F28F 27/00** (2013.01 - US); **F28F 2013/008** (2013.01 - EP US); **F28F 2265/10** (2013.01 - EP US);
F28F 2270/00 (2013.01 - EP US)

Citation (search report)
See references of WO 2008009812A1

Citation (examination)
• US 2006037589 A1 20060223 - GUPTA RAMESH [US], et al
• US 4281708 A 19810804 - WING LAWRENCE D, et al
• US 5379601 A 19950110 - GILLET JOHN B [US]

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA HR MK RS

DOCDB simple family (publication)
WO 2008009812 A1 20080124; BR PI0713191 A2 20120320; CA 2657778 A1 20080124; CA 2657778 C 20151124; CN 101490497 A 20090722; CN 101490497 B 20140723; EP 2047201 A1 20090415; EP 2047201 B1 20210901; FR 2904103 A1 20080125; FR 2904103 B1 20150515; JP 2009543998 A 20091210; RU 2009105501 A 20100827; RU 2460955 C2 20120910; US 2010012311 A1 20100121; US 2013098594 A1 20130425; US 9310145 B2 20160412

DOCDB simple family (application)
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